

Title (en)
THE METHOD OF MANUFACTURING A WIRE FROM CU-AL-MN-NI-FE ALLOY, ESPECIALLY FOR THE USE IN ADDITIVE MANUFACTURING

Title (de)
VERFAHREN ZUM HERSTELLEN EINES DRAHTES AUS EINER CU-AL-MN-HALB-LEGIERUNG, INSBESONDERE FÜR DIE VERWENDUNG IN DER GENERATIVEN FERTIGUNG

Title (fr)
PROCÉDÉ DE FABRICATION D'UN FIL À PARTIR D'UN ALLIAGE CU-AL-MN-NI-FE, EN PARTICULIER POUR L'UTILISATION DANS UNE FABRICATION ADDITIVE

Publication
EP 4060065 A1 20220921 (EN)

Application
EP 21000358 A 20211216

Priority
PL 43730421 A 20210315

Abstract (en)
The method of manufacturing a wire from Cu-Al -Mn-Ni-Fe alloy conducted by a multi-stage heat treatment in a protective atmosphere characterized in that after annealing at the temperature of 700-800 °C annealing of the semi-finished product at the temperature of 450-750 °C for 45 - 60 minutes is conducted, then it is etched in a pickling bath at the temperature of 50-60 °C for 50-60 minutes, and next it is rinsed and cleaned.

IPC 8 full level
C22C 9/01 (2006.01); **C22F 1/08** (2006.01); **C23G 1/10** (2006.01); **C23G 3/02** (2006.01)

CPC (source: EP PL)
B21C 37/047 (2013.01 - PL); **C22C 9/01** (2013.01 - EP PL); **C22C 9/05** (2013.01 - PL); **C22C 9/06** (2013.01 - PL); **C22F 1/08** (2013.01 - EP); **C23G 1/103** (2013.01 - EP); **C23G 3/021** (2013.01 - EP)

Citation (applicant)
US 3942582 A 19760309 - DOMPAS JOHN M, et al

Citation (search report)

- [Y] CN 111424190 A 20200717 - XINHUA HEANSHENG ELECTRONIC TECH CO LTD
- [Y] CN 107099804 A 20170829 - NANJING INST TECH
- [A] CN 109266874 A 20190125 - HENAN DALUN ELECTRONIC TECH CO LTD
- [T] "Metals Handbook Desk Edition", 31 December 1998, ASM INTERNATIONAL, ISBN: 978-1-62708-199-3, article DAVIES JOSEPH: "Surface Cleaning", pages: 1126 - 1135, XP055923820, DOI: 10.31399/asm.hb.mhde2.a0003213

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BA ME

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